Silicon N-channel IGBT

1. FEATURES

- * High speed, low loss IGBT module.
- * Low thermal impedance due to direct liquid cooling.
 * High reliability, high durability module.

2. ABSOLUTE MAXIMUM RATINGS (Tc=25°C)

Item	Symbol	Unit	Specification		
Collector Emitter Voltage	V_{CES}	V	650		
Gate Emitter Voltage	V_{GES}	V	±20		
Collector Current	DC	I _C	Α	600	
Collector Current	1ms	I _{Cp}	A	1200	
Forward Current	DC	I _F	Α	600	
Forward Current	1ms	I _{FM}	A	1200	
Maximum Junction Temperature	T _{imax}	°C	175		
Temperature under switching conditions	T _{jop}	°C	-40 ~ + 150		
Storage Temperature	T _{stg}	°C	-40 ~ +125		
Isolation Voltage	V _{ISO}	V_{RMS}	2,500 (AC 1 minute)		
Saraw Targua Terminals	Terminals (M6)		N⋅m	6.0 (1)	
Screw Torque Mounting (Mounting (M5)		111-111	4.0 (2)	

Notes: Recommended Value (1)5.5±0.5N·m (2)3.5±0.5N·m

3. ELECTRICAL CHARACTERISTICS

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Item		Symbol	Unit	Min.	Тур.	Max.	Test Conditions		
Collector Emitter Cut-Off Current		I _{CES}	mΑ	-	-	1.0	Vce=650V, Vge=0V, Tj=25°C		
Gate Emitter Leakage Current		I_{GES}	nA	-	-	±500	Vge=±20V, Vce=0V, Tj=25°C		
Collector Emitter Saturation Voltage		V _{CE(sat)}	V	1.3	1.65	2.1	Ic=600A, Vge=15V, Tj=25°C		
				-	1.9	-	Ic=600A, Vge=15V, Tj=150°C		
Gate Emitter Threshold Voltage		$V_{GE(TO)}$	V	6.0	6.7	7.5	Vce=5V, Ic=600mA, Tj=25°C		
Input Capacitance		C _{ies}	nF	-	53	-	Vce=10V, Vge=0V, f=100kHz, Tj=25°C		
Switching Times	Rise Time	t _r	- μs	-	0.15	0.4	Vcc=300V, Ic=600A		
	Turn On Time	t _{on}		-	0.50	0.9	Ls=30nH , R(ext)=4.7 Ω , Cge=56nF		
	Fall Time	t _f		-	0.35	0.8	Vge=+15V/0V, Tj=150°C		
	Turn Off Time	t _{off}		-	1.20	2.0	Inductive load		
Peak Forward Voltage Drop		V _F	V	1.1	1.45	1.8	If=600A, V _{GE} =0V, Tj=25°C		
				-	1.5	-	If=600A, V _{GE} =0V, Tj=150°C		
Reverse Recovery Time		t _{rr}	μS	-	0.35	0.8	V _{CC} =300V, Ic=600A,		
Turn On Loss		E _{on(full)}	mJ/P	-	20	30	Ls=30nH, Rg(ext)=4.7 Ω , Cge=56nF		
Turn Off Loss		E _{off(full)}	mJ/P	-	45	65	Vge=+15V/0V, Tj=150°C		
Reverse Recovery Loss		E _{rr(full)}	mJ/P	-	15	23	Inductive load		
Thermistor Resistance		R	kΩ	-	5	-	Tc=25 °C		
				-	0.16	-	Tc=150 °C		
Leakage Current between Thermistor and Other Terminals			mA	-	-	0.1	V=600Vp		
Thermal Resistance	IGBT	Rth(j-w)	K/W	-	-	0.145	Junction to water/fin, 10l/min, 50%LLC		
	FWD	Rth(j-w)	K/W	-	-	0.21	(per 1 arm)		

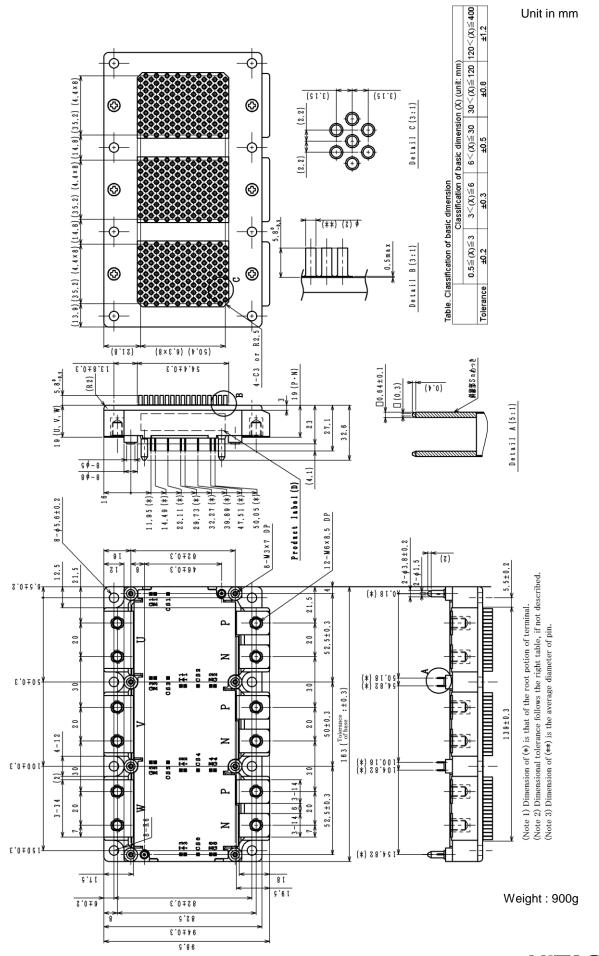
^{*} Please contact our representatives at order.



^{*} For improvement, specifications are subject to change without notice.

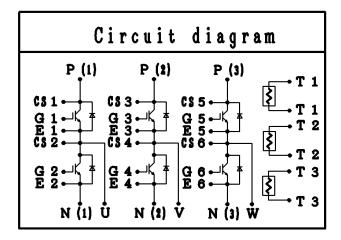
^{*} For actual application, please confirm this spec sheet is the newest revision.

4. PACKAGE OUTLINE DRAWING



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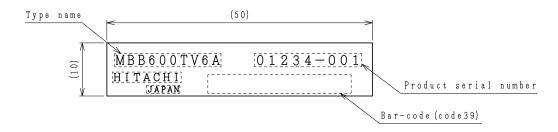
5. CIRCUIT DIAGRAM



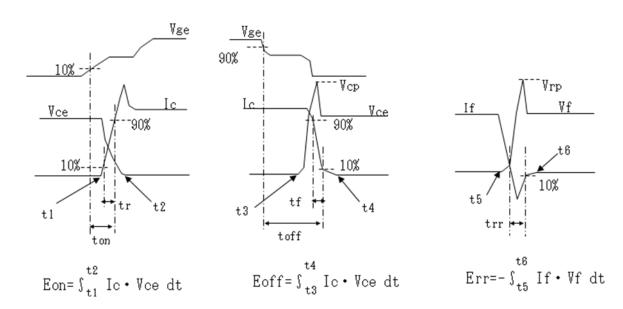
Thermistor T1, T2 and T3 are located on the same ceramic substrate with the IGBT and diode chips of phase U, V and W, respectively.

Note: This temperature measurement is not suitable for the short circuit or short term overload detection and should be used only for the module protection against long term overload or malfunction of the cooling system.

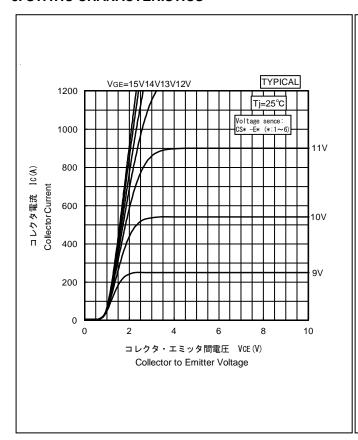
6. PRODUCT LABEL

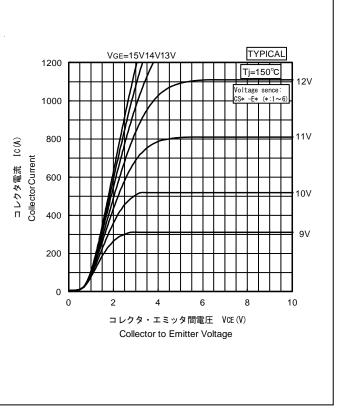


7. DEFINITION OF THE SYMBOLS



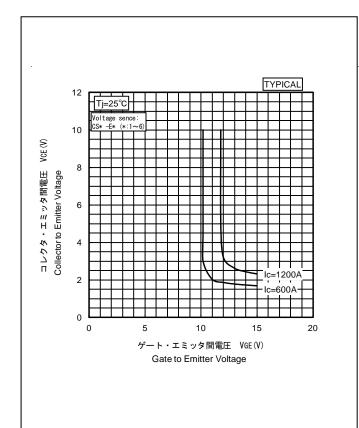
8. STATIC CHARACTERISTICS

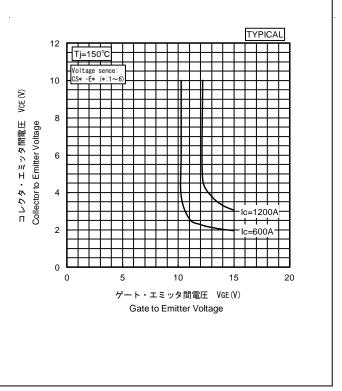




Collector Current vs. Collector to Emitter Voltage

Collector Current vs. Collector to Emitter Voltage

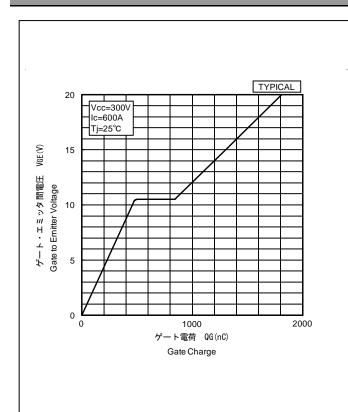


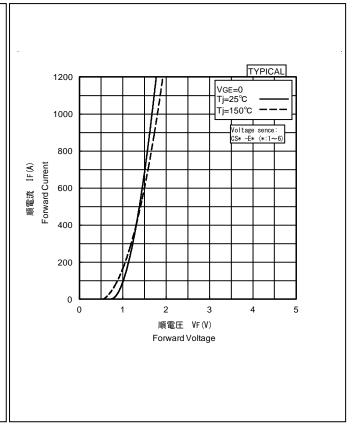


Collector to Emitter Voltage vs. Gate to Emitter Voltage

Collector to Emitter Voltage vs. Gate to Emitter Voltage



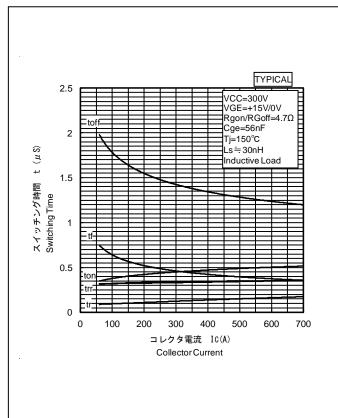


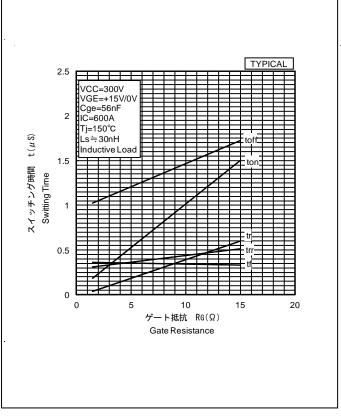


Gate Charge Characteristics

Forward Voltage of Free-Wheeling Diode

9. DYNAMIC CHARACTERISTICS

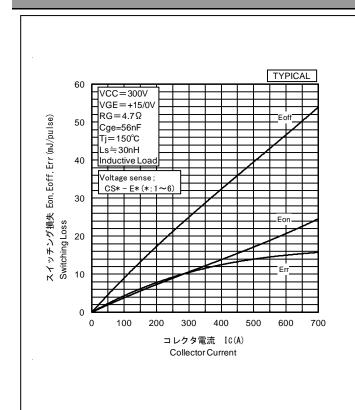


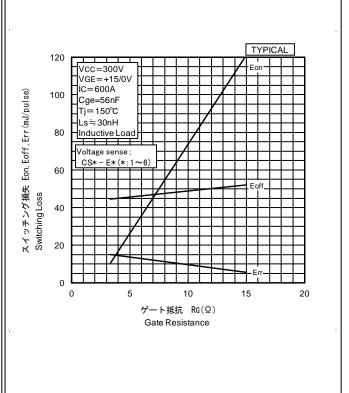


Switching Time vs. Collector Current

Switching Time vs. Gate Resistance

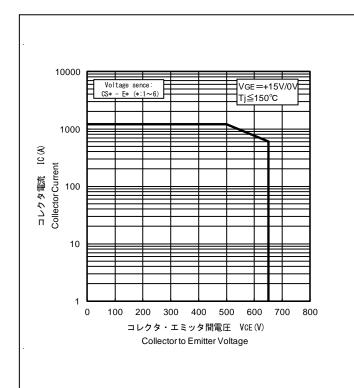


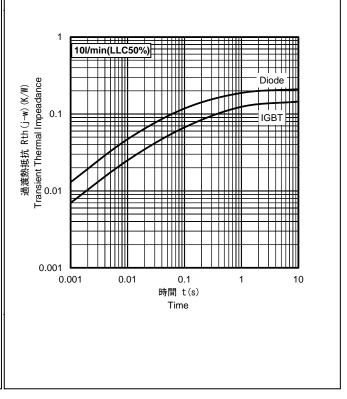




Switching Loss vs. Collector Current

Switching Loss vs. Gate Resistance

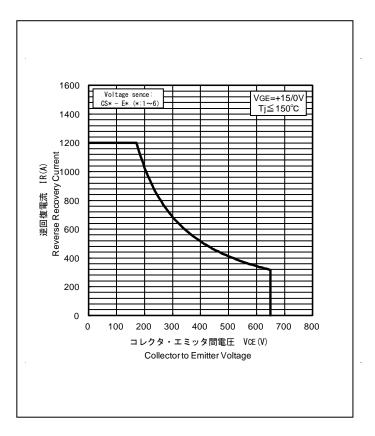




Reverse Bias Safe Operation Area (RBSOA)

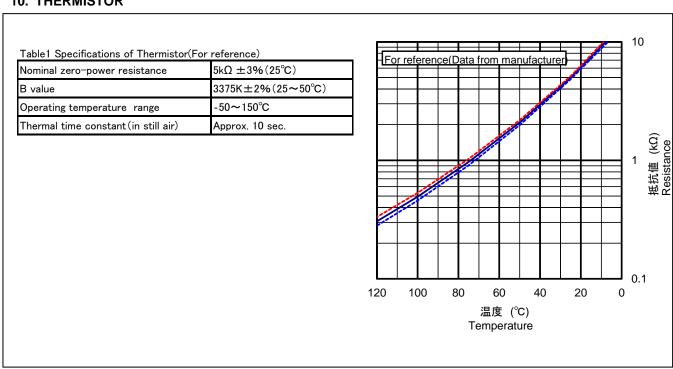
Transient Thermal Impedance Characteristics





Reverse Recovery Safe Operation Area (RRSOA)

10. THERMISTOR



Resistance vs. Temperature



HITACHI POWER SEMICONDUCTORS

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